

# Heatsink paste HSP 801

The heatsink paste **HSP 801** is a highly thermally conductive system simplifying the thermal management of pcbs/pcb assemblies.

- Base: Epoxy resin
- high-definition application by means of screen or stencil printing
- can be applied in variable structures and layer thicknesses
- cost-effective alternative to conventional glued heatsinks
- excellent adhesion to solder resists and various metallic substrates
- high mechanical resistance
- very good solder resistance
- good resistance in immersion tin

## Characteristics

The characteristics are indicated in the product-specific process data sheets which are enclosed with the first shipment of the product/sample, or transmitted upon request.

## Physical and mechanical properties

Property	Test method	Result
Thermal conductivity	ASTM D5470	3 W/mK
Pencil hardness	acc. to Wolff-Wilborn	≥ 7 H
Solvent resistance	IPC-TM-650, 2.3.42 Isopropanol Isopropanol (75 %) / H <sub>2</sub> O (25 %) monoethanolamine deionized H <sub>2</sub> O	passed passed passed passed
Water absorption	DIN EN ISO 62 (24 h/23 °C [73.4°F])	≤ 0.05 %
Solder bath resistance	IPC-SM-840E, 3.7.1/3.7.2 IPC-TM-650, 2.6.8	passed: 20 s at 265 °C [509 °F] passed: 10 s at 288 °C [550,4 °F]
Glass transition temperature T <sub>g</sub>	TMA, tension mode	≈ 156 °C [312,8 °F]
Thermal shock resistance	1000 cycles -40 / +150°C [-40 / 302 °F] (base material NP175 FBH)	no cracks, no delamination
Permanent temperature resistance	1000 h 150°C [302 °F]	no cracks, no delamination

## Electrical properties

Property	Test method	Result
Dielectric strength	IPC-TM-650, 2.5.6.1	$\geq 28$ kV/mm
Surface resistance	DIN EN 62631-3-2	$\geq 1,0 \times 10^{15}$ Ohm
Specific volume resistivity	DIN EN 62631-3-1	$\geq 4,7 \times 10^{14}$ Ohm x cm
Comparative Tracking Index (CTI)	DIN EN 60112 on base material with CTI 600	CTI $\geq 600^*$
Moisture and insulation resistance	IPC-SM-840E 3.9.1	$\geq 5 \times 10^8$ Ohm
	1500 h 65°C [149 °F]/93% r.F, 1000 Volt (Peters-Test)	$\geq 5 \times 10^8$ Ohm

\* Among others, the CTI value of the coating also depends upon the tracking resistance of the base material.

## Processing



Please read this technical report and the publications listed below carefully before using the product. These sheets are enclosed with the first shipment of product or sample.

### MSDS

The corresponding material safety data sheet contains detailed information and characteristics on safety precautions, environmental protection, transport, storage, handling and waste disposal.

### PD

The process data sheet contains product-specific data such as characteristics and recommendations for processing parameters.

### TI

[Technical information TI 15/3](#) "Protective measures when using chemicals including lacquers, casting compounds, thinners, cleaning agents"

### TI

[Technical information TI 15/13](#) "Pretreatment in the pcb fabrication process"

**Advice on pcb design: On account of the relatively high layer thickness of the heatsink paste, one should avoid printing solder paste directly next to the heatsink area in order to ensure a perfect solder paste print.**

**The heatsink paste is not suitable for printing on Pb/Sn surfaces which melt during soldering and cause the heatsink pastes to lift.**

**Given the relatively high layer thickness and the volume shrinkage related thereto, warpings may occur when thin substrates < 1 mm are coated.**

**Due to the large variety of chemical finish processes available and the fact that some of them are extremely aggressive, one must verify the compatibility by carrying out appropriate pre-trials.**

**Depending on the substrate to be printed, a more or less intense bleeding of the heatsink paste may occur. Therefore we recommend to test the bleeding behaviour in your respective application.**

Since the many different permutations make it impossible to evaluate the whole spectrum (parameters, reactions with materials used, chemical processes and machines) of processes and subsequent processes in all their variations, the parameters we recommend are to be viewed as guidelines only that were determined in laboratory conditions.

We advise you to determine the exact process limitations within your production environment, in particular as regards compatibility with your specific follow-up processes, in order to ensure a stable fabrication process and products of the highest possible quality.

The specified product data is based upon standard processing conditions/test conditions of the mentioned norms and must be verified if necessary while observing suitable test conditions on processed products.

Feel free to contact our application technology department (ATD) if you have any questions or for a consultation.

### Auxiliary products recommended

- [ELPESPEC® cleaning agent R 5899](#)  
for screen washing equipment, simply and safely to handle, no labelling in accordance with the German dangerous goods regulations required, extremely high flash point ( $> 100\text{ °C}$  [ $> 212\text{ °F}$ ]), low vapour pressure  $< 0.1\text{ hPa}$  at  $20\text{ °C}$  [ $68\text{ °F}$ ], thus not affected by the EU-VOC regulation 1999/13/CE
- [ELPESPEC® cleaning agent R 5821](#)  
for the cleaning of equipment and work tools, high flash point ( $+32\text{ °C}$  [ $89.6\text{ °F}$ ])
- [ELPESPEC® cleaning agent R 5817](#)  
for the manual cleaning of screens and tools

### Packaging

The packing units available are indicated in our offer which we will send you upon request.

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Any questions? We would be pleased to offer you advice and assistance in solving your problems. Samples and technical literature are available upon request.

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